

2N6027, 2N6028

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Power Dissipation* Derate Above 25°C	P _F 1/θ _{JA}	300 4.0	mW mW/°C
DC Forward Anode Current* Derate Above 25°C	I _T	150 2.67	mA mA/°C
DC Gate Current*	I _G	± 50	mA
Repetitive Peak Forward Current 100 μs Pulse Width, 1% Duty Cycle 20 μs Pulse Width, 1% Duty Cycle*	I _{TRM}	1.0 2.0	A
Non-Repetitive Peak Forward Current 10 μs Pulse Width	I _{TSM}	5.0	A
Gate to Cathode Forward Voltage*	V _{GKF}	40	V
Gate to Cathode Reverse Voltage*	V _{GKR}	- 5.0	V
Gate to Anode Reverse Voltage*	V _{GAR}	40	V
Anode to Cathode Voltage* (Note 1)	V _{AK}	±40	V
Capacitive Discharge Energy (Note 2)	E	250	μJ
Power Dissipation (Note 3)	P _D	300	mW
Operating Temperature	T _{OPR}	-50 to +100	°C
Junction Temperature	T _J	-50 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

*Indicates JEDEC Registered Data

1. Anode positive, R_{GA} = 1000 Ω
Anode negative, R_{GA} = open
2. E = 0.5 • CV² capacitor discharge energy limiting resistor and repetition.
3. Derate current and power above 25°C.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	R _{θJC}	75	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	200	°C/W
Maximum Lead Temperature for Soldering Purposes (< 1/16" from case, 10 seconds maximum)	T _L	260	°C

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ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Fig. No.	Symbol	Min	Typ	Max	Unit
Peak Current* (V _S = 10 Vdc, R _G = 1 MΩ) (V _S = 10 Vdc, R _G = 10 kΩ)	2,9,11	I _P	-	1.25 0.08	2.0 0.15	μA
Offset Voltage* (V _S = 10 Vdc, R _G = 1 MΩ) (V _S = 10 Vdc, R _G = 10 kΩ)	1	V _T	0.2 0.2 0.2	0.70 0.50 0.35	1.6 0.6 0.6	V
Valley Current* (V _S = 10 Vdc, R _G = 1 MΩ) (V _S = 10 Vdc, R _G = 10 kΩ) (V _S = 10 Vdc, R _G = 200 Ω)	1,4,5	I _V	- - 70 25 1.5 1.0	18 18 150 150 - -	50 25 - - - -	μA mA
Gate to Anode Leakage Current* (V _S = 40 Vdc, T _A = 25°C, Cathode Open) (V _S = 40 Vdc, T _A = 75°C, Cathode Open)	-	I _{GAO}	- -	1.0 3.0	10 -	nAdc
Gate to Cathode Leakage Current (V _S = 40 Vdc, Anode to Cathode Shorted)	-	I _{GKS}	-	5.0	50	nAdc
Forward Voltage* (I _F = 50 mA Peak) (Note 4)	1,6	V _F	-	0.8	1.5	V
Peak Output Voltage* (V _G = 20 Vdc, C _C = 0.2 μF)	3,7	V _O	6.0	11	-	V
Pulse Voltage Rise Time (V _B = 20 Vdc, C _C = 0.2 μF)	3	t _r	-	40	80	ns

*Indicates JEDEC Registered Data

4. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

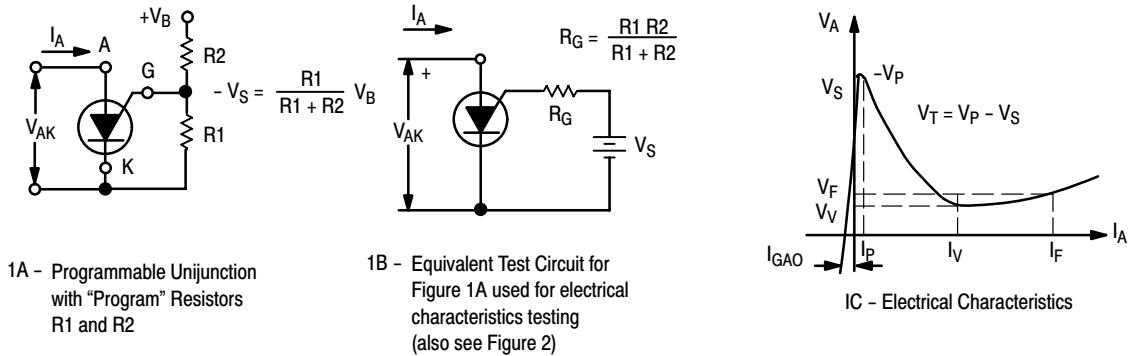


Figure 1. Electrical Characterization

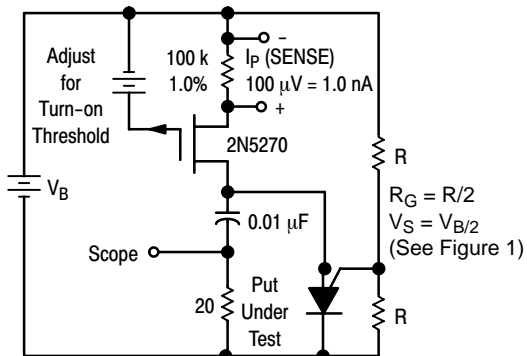


Figure 2. Peak Current (I_P) Test Circuit

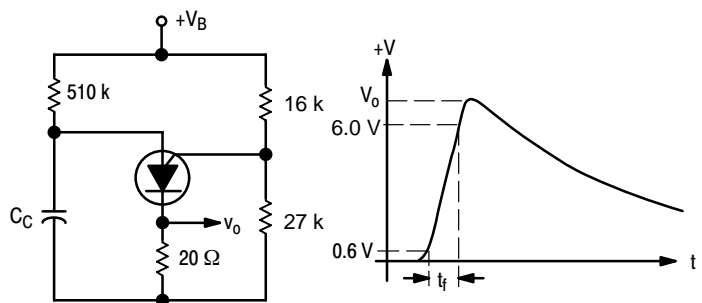


Figure 3. V_O and t_r Test Circuit

TYPICAL VALLEY CURRENT BEHAVIOR

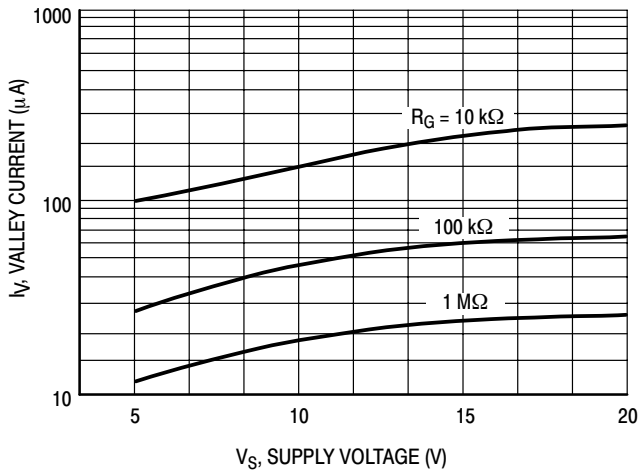


Figure 4. Effect of Supply Voltage

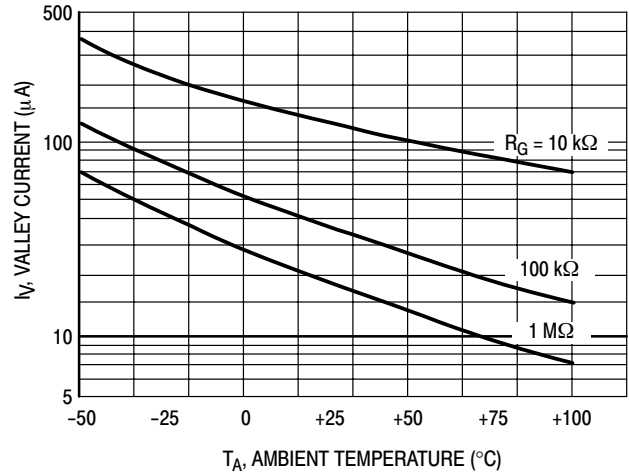


Figure 5. Effect of Temperature

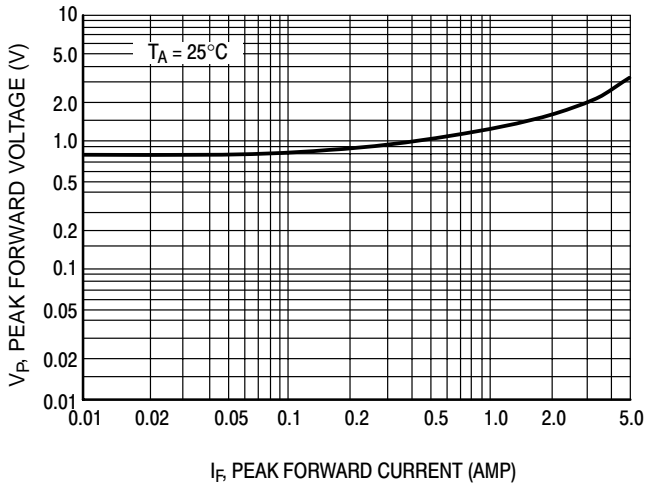


Figure 6. Forward Voltage

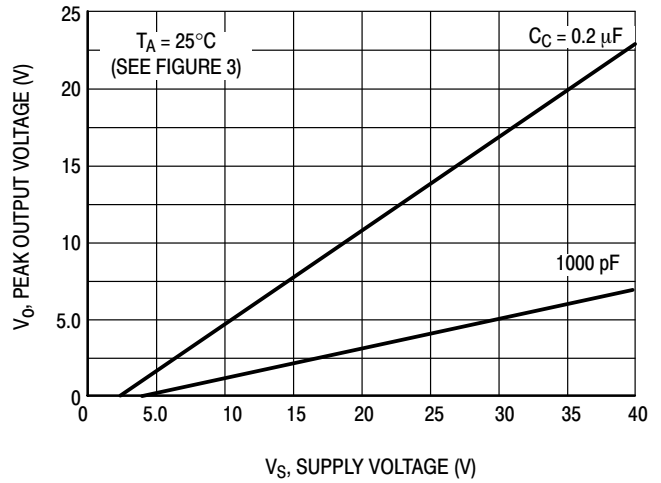


Figure 7. Peak Output Voltage

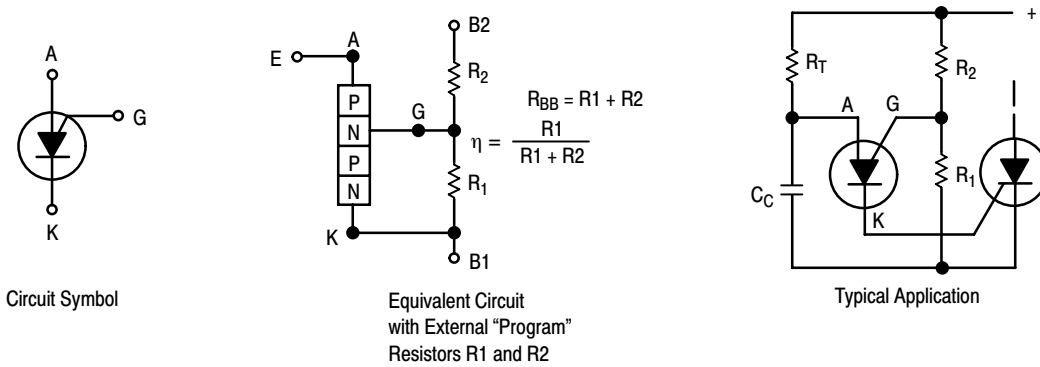


Figure 8. Programmable Unijunction

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TYPICAL PEAK CURRENT BEHAVIOR

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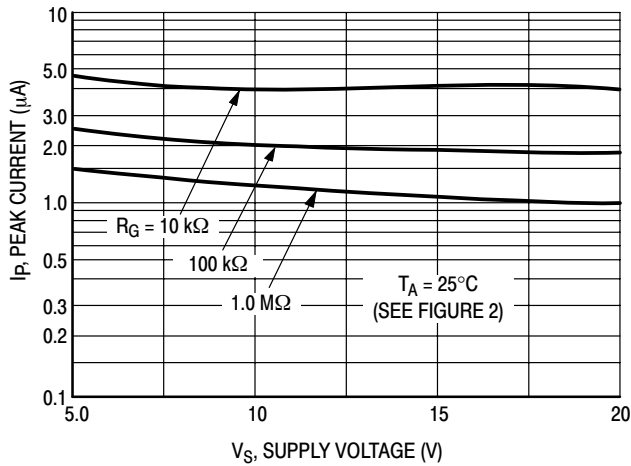


Figure 9. Effect of Supply Voltage and R_G

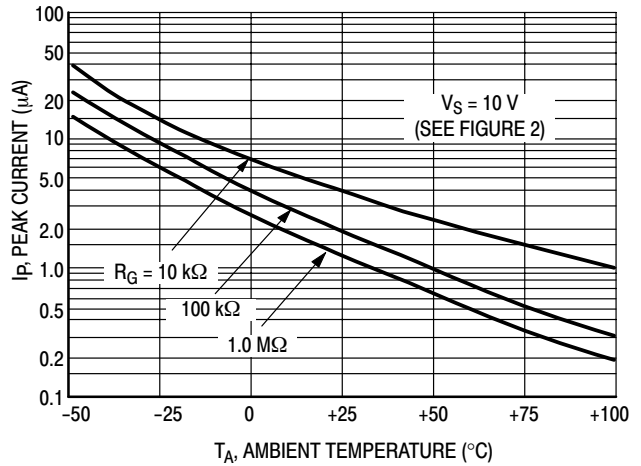


Figure 10. Effect of Temperature and R_G

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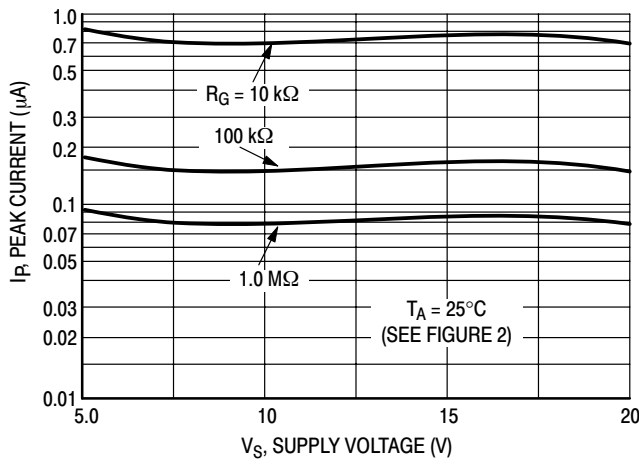


Figure 11. Effect of Supply Voltage and R_G

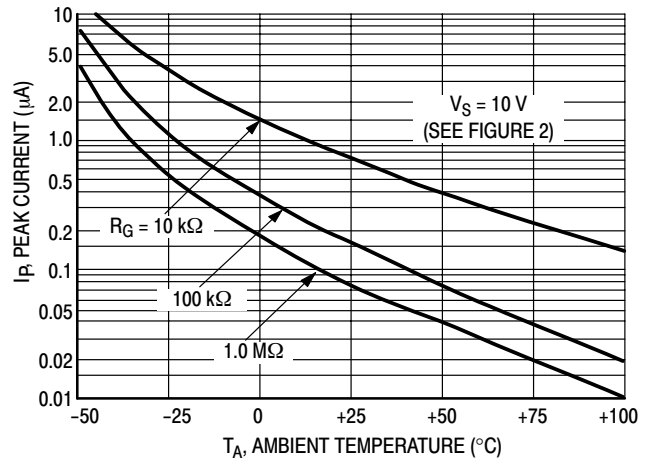


Figure 12. Effect of Temperature and R_G

ORDERING INFORMATION

U.S.	European Equivalent	Shipping [†]	Description of TO-92 Tape Orientation
2N6027	2N6027RL1 2N6027RL1G	5000 Units / Box	N/A – Bulk
2N6027G			
2N6028			
2N6028G			
2N6027RLRA		2000 / Tape & Reel	Round side of TO-92 and adhesive tape visible
2N6027RLRAG			
2N6028RLRA			
2N6028RLRAG			
2N6028RLRM		2000 / Tape & Ammo Box	Flat side of TO-92 and adhesive tape visible
2N6028RLRMG			
2N6028RLRP			Round side of TO-92 and adhesive tape visible
2N6028RLRPG			

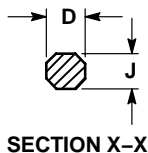
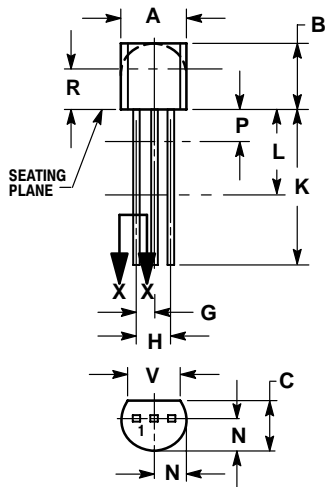
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*The "G" suffix indicates Pb-Free package available.

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PACKAGE DIMENSIONS

TO-92 (TO-226AA)
CASE 029-11
ISSUE AL



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---

STYLE 16:

1. ANODE
2. GATE
3. CATHODE

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